

RESIN COMPOSITION FOR MOLD CLEANING

ABSTRACT

A resin composition for mold cleaning is provided, in which the resin composition including: a melamine-based resin; a filler; an acidic compound; and at least one selected from the group consisting of an imide compound having a molecular weight of 500 or less and a urea compound having a molecular weight of 500 or less, the acidic compound being a compound that is different from the imide compound, and a mass ratio of a total content of the imide compound and the urea compound with respect to a content of the acidic compound being in a range of from 0.01 to 100.0.

[No suitable figure]